

## FEATURES

- ❑ 32K x 8 Static RAM with Chip Select Powerdown, Output Enable
- ❑ Auto-Powerdown™ Design
- ❑ Advanced CMOS Technology
- ❑ High Speed — to 15 ns maximum
- ❑ Low Power Operation
  - Active:
    - 380 mW (typical) at 45 ns
  - Standby (typical):
    - 10 mW (L7C199)
    - 1.25 mW (L7CL199)
- ❑ Data Retention at 2 V for Battery Backup Operation
- ❑ Plug Compatible with IDT71256, Cypress CY7C198/199
- ❑ Package Styles Available:
  - 28-pin Plastic DIP
  - 28-pin Sidebraze, Hermetic DIP
  - 28-pin CerDIP
  - 28-pin Plastic SOIC
  - 28-pin Plastic SOJ
  - 32-pin Ceramic LCC

## DESCRIPTION

The L7C199 and L7CL199 are high-performance, low-power CMOS static RAMs. The storage circuitry is organized as 32,768 words by 8 bits per word. The 8 Data In and Data Out signals share I/O pins. These devices are available in five speeds with maximum access times from 15 ns to 45 ns.

Inputs and output are TTL compatible. Operation is from a single +5 V power supply. Power consumption for the L7C199 is 380 mW (typical) at 45 ns. Dissipation drops to 100 mW (typical) for the L7C199 and 60 mW (typical) for the L7CL199 when the memory is deselected (Enable is high).

Two standby modes are available. Proprietary Auto-Powerdown™ circuitry reduces power consumption automatically during read or write accesses which are longer than the minimum access time, or when the memory is deselected. In addition,

data may be retained in inactive storage with a supply voltage as low as 2 V. The L7C199 and L7CL199 consume only 1.5 mW (typical) at 3 V, allowing effective battery backup operation.

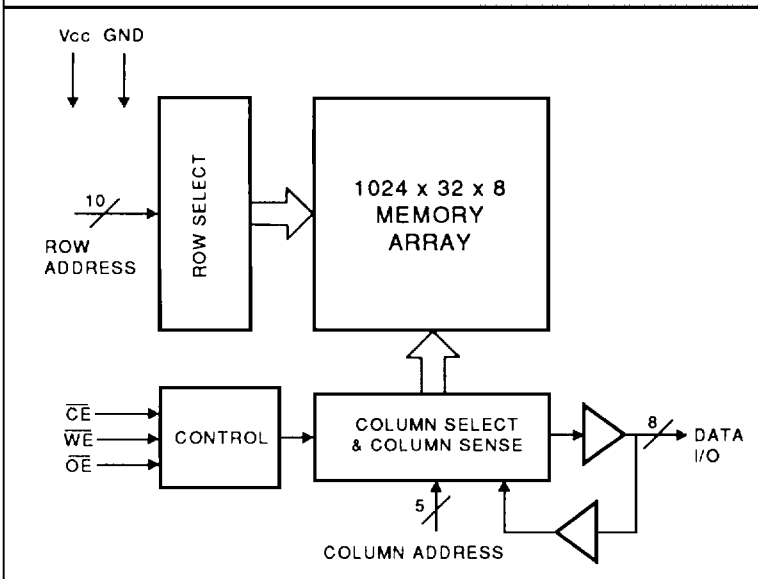
The L7C199 and L7CL199 provide asynchronous (unlocked) operation with matching access and cycle times. An active-low Chip Enable and a three-state I/O bus with a separate Output Enable control simplify the connection of several chips for increased storage capacity.

Memory locations are specified on address pins A0 through A14. Reading from a designated location is accomplished by presenting an address and driving  $\overline{CE}$  low while  $\overline{WE}$  remains high. The data in the addressed memory location will then appear on the Data Out pin within one access time. The output pin stays in a high-impedance state when  $\overline{CE}$  or  $\overline{OE}$  is high, or  $\overline{WE}$  is low.

Writing to an addressed location is accomplished when the active-low  $\overline{CE}$  and  $\overline{WE}$  inputs are both low. Either signal may be used to terminate the write operation. Data In and Data Out signals have the same polarity.

Latchup and static discharge protection are provided on-chip. The L7C199 and L7CL199 can withstand an injection current of up to 200 mA on any pin without damage.

**L7C199/L7CL199 Block Diagram**



**MAXIMUM RATINGS** Above which useful life may be impaired (Notes 1, 2)

Storage temperature .....	-65°C to +150°C
Operating ambient temperature .....	-55°C to +125°C
V <sub>CC</sub> supply voltage with respect to ground .....	-0.5 V to +7.0 V
Input signal with respect to ground .....	-3.0 V to +7.0 V
Signal applied to high impedance output .....	-3.0 V to +7.0 V
Output current into low outputs .....	25 mA
Latchup current .....	> 200 mA

**OPERATING CONDITIONS** To meet specified electrical and switching characteristics

Mode	Temperature Range (Ambient)	Supply Voltage
Active Operation, Commercial	0°C to +70°C	4.5 V ≤ V <sub>CC</sub> ≤ 5.5 V
Active Operation, Military	-55°C to +125°C	4.5 V ≤ V <sub>CC</sub> ≤ 5.5 V
Data Retention, Commercial	0°C to +70°C	2.0 V ≤ V <sub>CC</sub> ≤ 5.5 V
Data Retention, Military	-55°C to +125°C	2.0 V ≤ V <sub>CC</sub> ≤ 5.5 V

**ELECTRICAL CHARACTERISTICS** Over Operating Conditions (Note 5)

Symbol	Parameter	Test Condition	L7C199			L7CL199			Unit
			Min	Typ	Max	Min	Typ	Max	
V <sub>OH</sub>	Output High Voltage	I <sub>OH</sub> = -4.0 mA, V <sub>CC</sub> = 4.5 V	2.4			2.4			V
V <sub>OL</sub>	Output Low Voltage	I <sub>OL</sub> = 8.0 mA			0.4			0.4	V
V <sub>IH</sub>	Input High Voltage		2.0		V <sub>CC</sub> + 0.3	2.0		V <sub>CC</sub> + 0.3	V
V <sub>IL</sub>	Input Low Voltage	(Note 3)	-3.0		0.8	-3.0		0.8	V
I <sub>IX</sub>	Input Leakage Current	GND ≤ V <sub>IN</sub> ≤ V <sub>CC</sub>	-10		+10	-10		+10	μA
I <sub>OZ</sub>	Output Leakage Current	GND ≤ V <sub>OUT</sub> ≤ V <sub>CC</sub> , CE = V <sub>CC</sub>	-10		+10	-10		+10	μA
I <sub>OS</sub>	Output Short Current	V <sub>OUT</sub> = GND, V <sub>CC</sub> = Max (Note 4)			-350			-350	mA
I <sub>CC2</sub>	V <sub>CC</sub> Current, TTL Inactive	(Note 7)		20	40		12	20	mA
I <sub>CC3</sub>	V <sub>CC</sub> Current, CMOS Standby	(Note 8)		2	10		0.25	0.75	mA
I <sub>CC4</sub>	V <sub>CC</sub> Current, Data Retention	V <sub>CC</sub> = 3.0 V (Note 9)		500	5000		20	200	μA
C <sub>IN</sub>	Input Capacitance	Ambient Temp = 25°C, V <sub>CC</sub> = 5.0 V			5			5	pF
C <sub>OUT</sub>	Output Capacitance	Test Frequency = 1 MHz (Note 10)			7			7	pF

Symbol	Parameter	Test Condition	L7C199/L7CL199-					Unit
			45	35	25	20	15	
I <sub>CC1</sub>	V <sub>CC</sub> Current, Active	(Note 6)	85	110	150	185	240	mA

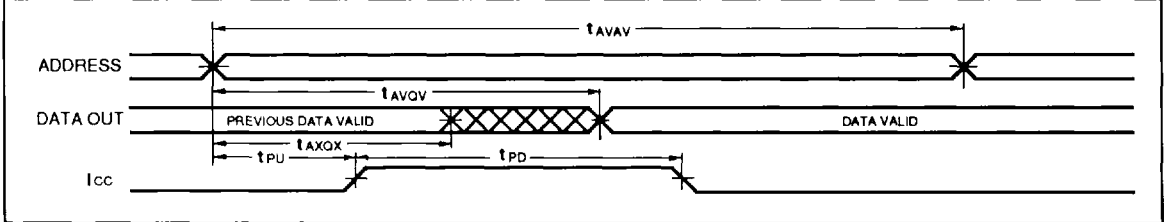


**SWITCHING CHARACTERISTICS** *Over Operating Range (ns)*

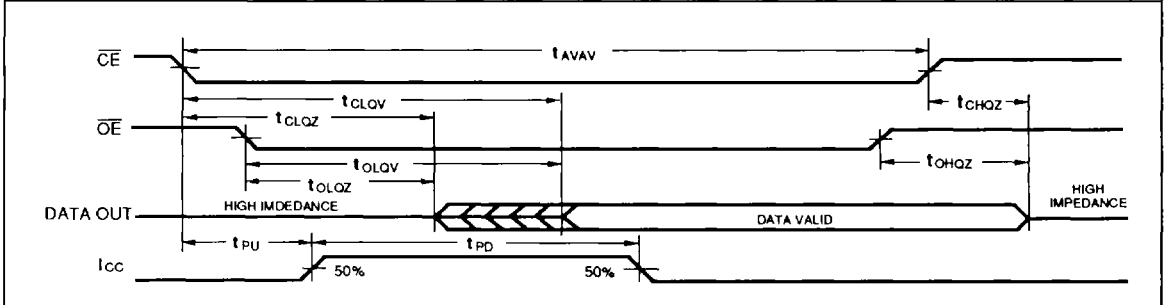
**READ CYCLE** (Notes 5, 11, 12, 22, 23, 24)

Symbol	Parameter	L7C199/L7CL199-									
		45		35		25		20		15	
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max
t <sub>AVAV</sub>	Read Cycle Time	45		35		25		20		15	
t <sub>AVQV</sub>	Address Valid to Output Valid (13, 14)		45		35		25		20		15
t <sub>AXOX</sub>	Address Change to Output Change	3		3		3		3		3	
t <sub>CLOV</sub>	Chip Enable Low to Output Valid (13, 15)		45		35		25		20		15
t <sub>CLOZ</sub>	Chip Enable Low to Output Low Z (20, 21)	3		3		3		3		3	
t <sub>CHOZ</sub>	Chip Enable High to Output High Z (20, 21)		15		15		10		8		8
t <sub>OLQV</sub>	Output Enable Low to Output Valid		20		15		12		10		8
t <sub>LOZ</sub>	Output Enable Low to Output Low Z (20, 21)	0		0		0		0		0	
t <sub>HOZ</sub>	Output Enable High to Output High Z (20, 21)		15		10		10		8		5
t <sub>PU</sub>	Input Transition to Power Up (10, 19)	0		0		0		0		0	
t <sub>PD</sub>	Power Up to Power Down (10, 19)		45		35		25		20		20
t <sub>CHVL</sub>	Chip Enable High to Data Retention (10)	0		0		0		0		0	

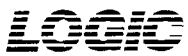
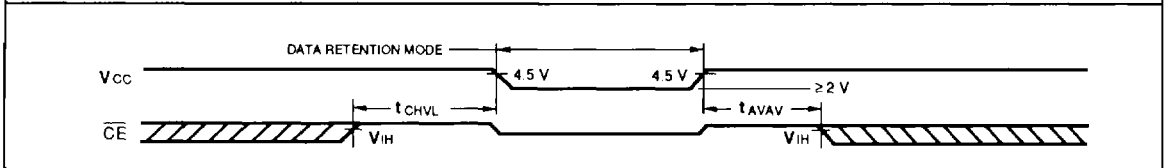
**READ CYCLE — ADDRESS CONTROLLED** (Notes 13, 14)



**READ CYCLE — CE/OE CONTROLLED** (Notes 13, 15)



**DATA RETENTION**



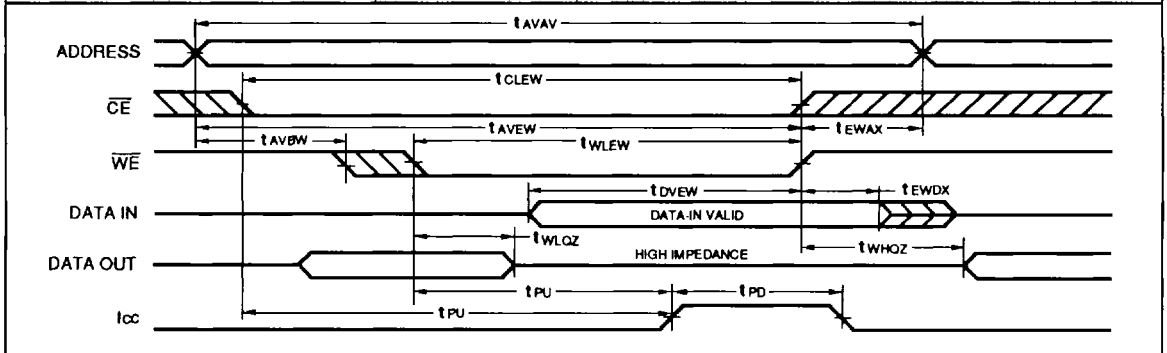
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**SWITCHING CHARACTERISTICS** *Over Operating Range (ns)*

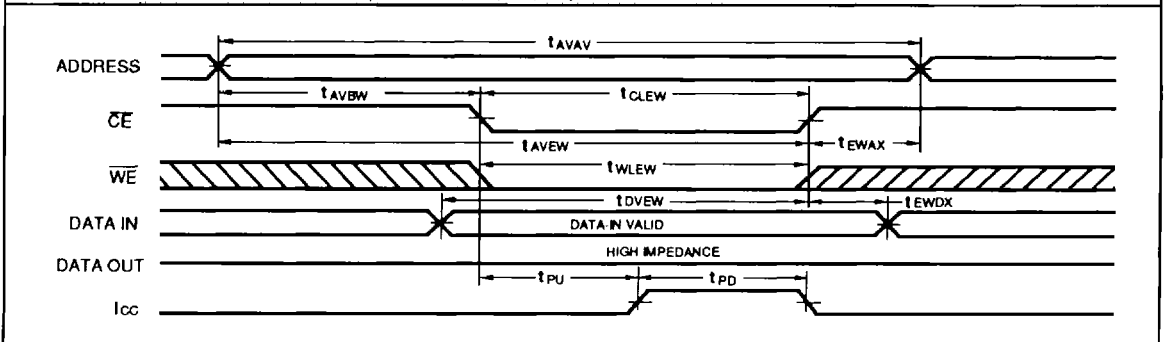
**WRITE CYCLE** (Notes 5, 11, 12, 22, 23, 24)

Symbol	Parameter	L7C199/L7CL199-									
		45		35		25		20		15	
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max
tAVAV	Write Cycle Time	40		25		20		20		15	
tCLEW	Chip Enable Low to End of Write Cycle	30		25		15		15		12	
tAVBW	Address Valid to Beginning of Write Cycle	0		0		0		0		0	
tAVEV	Address Valid to End of Write Cycle	30		25		15		15		12	
tEWAX	End of Write Cycle to Address Change	0		0		0		0		0	
twLEW	Write Enable Low to End of Write Cycle	20		20		15		15		12	
tDVEV	Data Valid to End of Write Cycle	15		15		10		10		7	
tEWDX	End of Write Cycle to Data Change	0		0		0		0		0	
tWHQZ	Write Enable High to Output Low Z (20, 21)	0		0		0		0		0	
twLOZ	Write Enable Low to Output High Z (20, 21)		15		10		7		7		5

**WRITE CYCLE — WE CONTROLLED** (Notes 16, 17, 18, 19)



**WRITE CYCLE — CE CONTROLLED** (Notes 16, 17, 18, 19)



## NOTES

1. Maximum Ratings indicate stress specifications only. Functional operation of these products at values beyond those indicated in the Operating Conditions table is not implied. Exposure to maximum rating conditions for extended periods may affect reliability of the tested device.
2. The products described by this specification include internal circuitry designed to protect the chip from damaging substrate injection currents and accumulations of static charge. Nevertheless, conventional precautions should be observed during storage, handling, and use of these circuits in order to avoid exposure to excessive electrical stress values.
3. This product provides hard clamping of transient undershoot. Input levels below ground will be clamped beginning at  $-0.6$  V. A current in excess of 100 mA is required to reach  $-2$  V. The device can withstand indefinite operation with inputs as low as  $-3$  V subject only to power dissipation and bond wire fusing constraints.
4. Duration of the output short circuit should not exceed 30 seconds.
5. A series of normalized curves on pages 2-8 through 2-11 of this data book supply the designer with typical DC and AC parametric information for Logic Devices Static RAMs. These curves may be used to determine device characteristics at various temperatures and voltage levels.
6. Tested with all address and data inputs changing at the maximum cycle rate. The device is continuously enabled for writing, i.e.,  $CE \leq V_{II}$ ,  $WE \leq V_{II}$ . Input pulse levels are 0 to 3.0 V.
7. Tested with outputs open and all address and data inputs changing at the maximum read cycle rate. The device is continuously disabled, i.e.,  $CE \geq V_{III}$ .
8. Tested with outputs open and all address and data inputs stable. The device is continuously disabled, i.e.,  $CE = V_{CC}$ . Input levels are within 0.2 V of VCC or ground.
9. Data retention operation requires that VCC never drop below 2.0 V.  $CE1$  must be  $\geq V_{CC} - 0.2$  V. For the L7C199, all other inputs meet  $V_{IN} \leq 0.2$  V or  $V_{IN} \geq V_{CC} - 0.2$  V to ensure full powerdown. For the L7CL199, this requirement applies only to  $CE$  and  $WE$ ; there are no restrictions on data and address.
10. These parameters are guaranteed but not 100% tested.
11. Test conditions assume input transition times of less than 3 ns, reference levels of 1.5 V, output loading for specified IOL and IOH plus 30 pF (Fig. 1a), and input pulse levels of 0 to 3.0 V (Fig. 2).
12. Each parameter is shown as a minimum or maximum value. Input requirements are specified from the point of view of the external system driving the chip. For example,  $t_{AVW}$  is specified as a minimum since the external system must supply at least that much time to meet the worst-case requirements of all parts. Responses from the internal circuitry are specified from the point of view of the device. Access time, for example, is specified as a maximum since worst-case operation of any device always provides data within that time.
13.  $WE$  is high for the read cycle.
14. The chip is continuously selected ( $CE$  low).
15. All address lines are valid prior to or coincident with the  $CE$  transition to low.
16. The internal write cycle of the memory is defined by the overlap of  $CE$  low and  $WE$  low. Both signals must be low to initiate a write. Either signal can terminate a write by going high. The address, data, and control input setup and hold times should be referenced to the signal that falls last or rises first.
17. If  $WE$  goes low before or concurrent with  $CE$  going low, the output remains in a high impedance state.
18. If  $CE$  goes high before or concurrent with  $WE$  going high, the output remains in a high impedance state.
19. Powerup from ICC2 to ICC1 occurs as a result of any of the following conditions:
  - a. Falling edge of  $CE$ .
  - b. Falling edge of  $WE$  ( $CE$  active).
  - c. Transition on any address line ( $CE$  active).
  - d. Transition on any data line ( $CE$  and  $WE$  active).

The device automatically powers down from ICC2 to ICC1 after  $t_{\text{tr0}}$  has elapsed from any of the prior conditions. This means that power dissipation is dependent on only cycle rate, and is not on Chip Select pulse width.
20. At any given temperature and voltage condition, output disable time is less than output enable time for any given device.

21. Transition is measured  $\pm 200$  mV from steady state voltage with specified loading in Fig. 1b. This parameter is sampled and not 100% tested.

22. All address timings are referenced from the last valid address line to the first transitioning address line.

23.  $CE$  or  $WE$  must be high during address transitions.

24. This product is a very high speed device and care must be taken during testing in order to realize valid test information. Inadequate attention to setups and procedures can cause a good part to be rejected as faulty. Long high inductance leads that cause supply bounce must be avoided by bringing the VCC and ground planes directly up to the contactor fingers. A 0.01  $\mu$ F high frequency capacitor is also required between VCC and ground. To avoid signal reflections, proper terminations must be used.

FIGURE 1a.

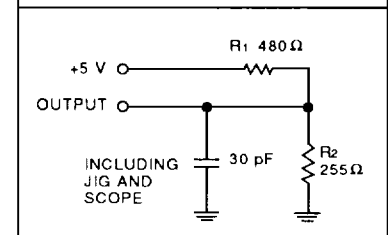


FIGURE 1b.

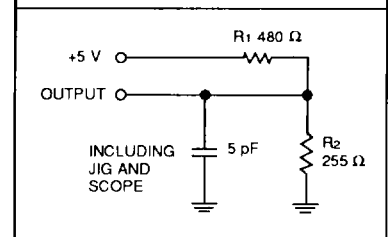
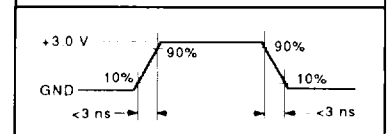
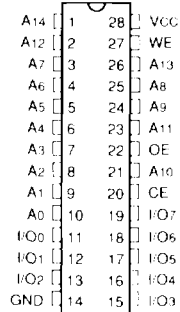


FIGURE 2.

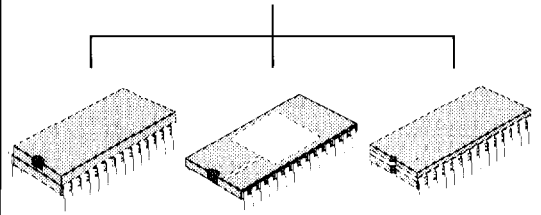
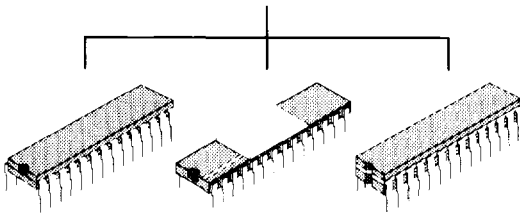
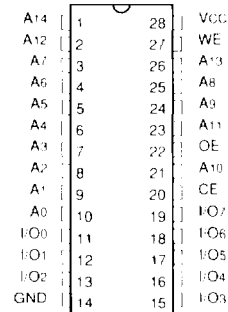


**ORDERING INFORMATION**

**28-pin  
(0.3" wide)**



**28-pin  
(0.6" wide)**



Speed	Plastic DIP (P10)	Sidebrazed Hermetic DIP (D10)	CerDIP (C5)	Plastic DIP (P9)	Sidebrazed Hermetic DIP (D9)	CerDIP (C6)
<b>0°C to +70°C — COMMERCIAL SCREENING</b>						
45 ns 35 ns 25 ns 20 ns 15 ns 12 ns	L7C199PC or L7CL199PC	L7C199DC or L7CL199DC	L7C199CC or L7CL199CC	L7C199NC or L7CL199NC	L7C199HC or L7CL199HC	L7C199IC or L7CL199IC
<b>-55°C to +125°C — COMMERCIAL SCREENING</b>						
45 ns 35 ns 25 ns 20 ns 15 ns 12 ns		L7C199DM or L7CL199DM	L7C199CM or L7CL199CM		L7C199HM or L7CL199HM	L7C199IM or L7CL199IM
<b>-55°C to +125°C — EXTENDED SCREENING</b>						
45 ns 35 ns 25 ns 20 ns 15 ns 12 ns		L7C199DME or L7CL199DME	L7C199CME or L7CL199CME		L7C199HME or L7CL199HME	L7C199IME or L7CL199IME
<b>-55°C to +125°C — MIL-STD-883 COMPLIANT</b>						
45 ns 35 ns 25 ns 20 ns 15 ns 12 ns		L7C199DMB or L7CL199DMB	L7C199CMB or L7CL199CMB		L7C199HMB or L7CL199HMB	L7C199IMB or L7CL199IMB



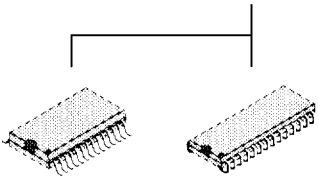
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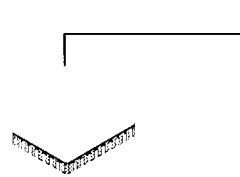
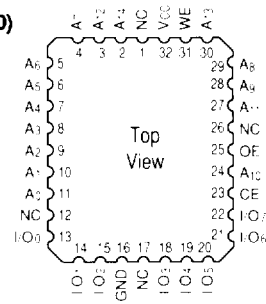
**ORDERING INFORMATION**

**28-pin**

A14	1	28	VCC
A12	2	27	WE
A7	3	26	A13
A6	4	25	A8
A5	5	24	A9
A4	6	23	A11
A3	7	22	OE
A2	8	21	A10
A1	9	20	CE
A0	10	19	I/O7
I/O0	11	18	I/O6
I/O1	12	17	I/O5
I/O2	13	16	I/O4
GND	14	15	I/O3



**32-pin  
(450 x 550)**



Speed	Plastic SOIC (.340" — V2)	Plastic SOJ (.300" — W2)	Ceramic Leadless Chip Carrier (K7)
<b>0°C to +70°C — COMMERCIAL SCREENING</b>			
45 ns 35 ns 25 ns 20 ns 15 ns 12 ns	L7C199VC { 45 35 25 20 15 } or L7CL199VC	L7C199WC { 45 35 25 20 15 } or L7CL199WC	L7C199TC { 45 35 25 20 15 } or L7CL199TC
<b>-55°C to +125°C — COMMERCIAL SCREENING</b>			
45 ns 35 ns 25 ns 20 ns 15 ns 12 ns			L7C199TM { 45 35 25 20 } or L7CL199TM
<b>-55°C to +125°C — EXTENDED SCREENING</b>			
45 ns 35 ns 25 ns 20 ns 15 ns 12 ns			L7C199TME { 45 35 25 20 } or L7CL199TME
<b>-55°C to +125°C — MIL-STD-883 COMPLIANT</b>			
45 ns 35 ns 25 ns 20 ns 15 ns 12 ns			L7C199TMB { 45 35 25 20 } or L7CL199TMB